

L Number	Hits	Search Text	DB	Time stamp
8	1080	thermoele\$6 with (tip\$4 point\$4 apex\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/11 12:43
1	156	(ghoshal).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/11 09:53
15	65	(uttam with ghoshal).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/11 09:54
22	55	(uttam with ghoshal).in.	USPAT; US-PGPUB	2003/03/11 10:06
25	13	(thermoele\$6 with (tip\$4 point\$4 apex\$4)) and ((uttam with ghoshal).in.)	USPAT; US-PGPUB	2003/03/11 10:06
35	54	(thermoele\$6 near3 (tip\$4 point\$4 apex\$4)) and (fused fusing solder\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/11 12:01
42	13	(thermoele\$6 near3 (tip\$4 point\$4 apex\$4)) and (fused fusing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/11 12:01
49	79	thermoele\$6 with (fusing fused)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/11 12:17
28	273	thermoele\$6 near3 (tip\$4 point\$4 apex\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/11 12:30
63	152	thermoele\$6 near3 (tip\$4 point\$4 apex\$4)	USPAT	2003/03/11 12:31
64	1124	((136/201) or (136/203) or (62/3.2)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/11 12:42
71	28	(thermoele\$6 near3 (tip\$4 point\$4 apex\$4)) and (((136/201) or (136/203) or (62/3.2)).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/11 12:37

78	6	("5130276") or ("5279128") or ("5867990") or ("5966941") or ("6000225") or ("6161388")).PN.	USPAT	2003/03/11 12:39
79	26	(228/134).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/11 12:43
86	0	(thermoele\$6 with (tip\$4 point\$4 apex\$4)) and ((228/134).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/11 12:43
93	27	thermoele\$6and ((228/134).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/11 12:43
100	0	thermoele\$6 and ((228/134).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/11 12:44
107	36264	(228/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/11 12:44
114	47	thermoele\$6 and ((228/\$).ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/11 12:44
-	18212	thermoelectric\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/11 09:14
-	36256	(228/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:34
-	42	thermoelectric\$5 and ((228/\$).ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 15:23
-	4807	thermoelectric\$5 near2 cool\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 15:19

-	13	(thermoelectric\$5 near2 cool\$5) and ((228/\$).ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 15:24
-	60647	circuit\$5 with cool\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 15:25
-	1013981	computer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 15:25
-	3792	peltier with effect	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 15:27
-	52	(thermoelectric\$5 near2 cool\$5) and (circuit\$5 with cool\$5) and computer and (peltier with effect)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 15:33
-	88	((ghoshal).in.) and ((thermoelectric\$5 near2 cool\$5) (circuit\$5 with cool\$5) computer (peltier with effect))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 15:39
-	9	substrate same (point tip) same (metal metallic) same (insulate insulation insulating) same thermoele\$6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:05
-	735	(thermoelectric\$5 near2 cool\$5) and (peltier with effect)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 15:43
-	6554	substrate with (point\$5 tip\$5) with (silicon si copper cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:02
-	230490	(metal metallic metallized metallization) with (titanium ti platinum pt)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:02

17322	insulat\$5 with (silicon adj2 dioxide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:03
360197	dielectric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:03
415352	etch\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:03
475	thermoele\$5 with (coat\$5 overcoat\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:03
211858	electrochem\$5 cvd (chemical adj vapor adj deposit\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:04
1378	thermoele\$5 with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:04
331678	fuse fusing fused	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:06
175	(substrate with (point\$5 tip\$5) with (silicon si copper cu)) and ((metal metallic metallized metallization) with (titanium ti platinum pt)) and (insulat\$5 with (silicon adj2 dioxide))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:06
115	(thermoele\$5 with substrate) and (fuse fusing fused)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:07
10	((substrate with (point\$5 tip\$5) with (silicon si copper cu)) and ((metal metallic metallized metallization) with (titanium ti platinum pt)) and (insulat\$5 with (silicon adj2 dioxide))) ((thermoele\$5 with substrate) and (fuse fusing fused))) and (thermoele\$5 with (coat\$5 overcoat\$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:07

65	(uttam with ghoshal).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:31
40	thermoelement with cooler	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:32
2593	thermoelectric with cooler	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:32
2216	thermoelectric adj2 cooler	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:33
35	(thermoelectric adj2 cooler) and thermoelement	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:34
76844	(62/\$).cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:34
11985	(136/\$).cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:34
390	(((62/\$).cccls.) ((228/\$).cccls.) ((136/\$).cccls.)) and (thermoelectric with cooler)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:42
283	(((62/\$).cccls.) ((228/\$).cccls.) ((136/\$).cccls.)) and (thermoelectric adj2 cooler)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:35
13	(((62/\$).cccls.) ((228/\$).cccls.) ((136/\$).cccls.)) and (thermoelectric adj2 cooler)) and (fusing fused)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 16:38

4	("6403876") or ("6222113")).PN.	USPAT;	2003/03/07
		US-PGPUB;	16:39
		EPO; JPO;	
		DERWENT;	
		IBM_TDB	
14	(US-5734270-\$ or US-6388185-\$ or US-6347521-\$ or US-5864087-\$ or US-4497973-\$ or US-6467951-\$ or US-6467275-\$ or US-6403876-\$ or US-6384312-\$ or US-6369314-\$ or US-6065293-\$ or US-6222113-\$).did. or (US-20020166839-\$ or US-20020092557-\$).did.	USPAT;	2003/03/07
		US-PGPUB	16:41
90	peltier with thermoelement	USPAT;	2003/03/07
		US-PGPUB;	16:41
		EPO; JPO;	
		DERWENT;	
		IBM_TDB	
15	((62/\$).ccls.) ((228/\$).ccls.) ((136/\$).ccls.) and (peltier with thermoelement)	USPAT;	2003/03/07
		US-PGPUB;	16:46
		EPO; JPO;	
		DERWENT;	
		IBM_TDB	
5	("6000225") or ("5966941") or ("5279128") or ("5130276") or ("6161388")).PN.	USPAT	2003/03/07
			17:14
2085	substrate with (point\$5 tip\$5) with (metal metallic silicon si copper cu) with (insulat\$5 (silicon adj dioxide))	USPAT;	2003/03/07
		US-PGPUB;	17:19
		EPO; JPO;	
		DERWENT;	
		IBM_TDB	
70	substrate with thermoele\$7 with (coat\$5 overcoat\$5 over-coat\$5)	USPAT;	2003/03/07
		US-PGPUB;	17:27
		EPO; JPO;	
		DERWENT;	
		IBM_TDB	
1	(substrate with (point\$5 tip\$5) with (metal metallic silicon si copper cu) with (insulat\$5 (silicon adj dioxide))) and (substrate with thermoele\$7 with (coat\$5 overcoat\$5 over-coat\$5))	USPAT;	2003/03/07
		US-PGPUB;	17:28
		EPO; JPO;	
		DERWENT;	
		IBM_TDB	
69	computer with (thermoelectric\$5 adj2 cool\$6)	USPAT;	2003/03/07
		US-PGPUB;	17:31
		EPO; JPO;	
		DERWENT;	
		IBM_TDB	
251	(method process) with thermoelement	USPAT;	2003/03/07
		US-PGPUB;	17:33
		EPO; JPO;	
		DERWENT;	
		IBM_TDB	

473	(method process\$5) with (thermoelectric\$5 adj2 cool\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 17:33
272	(method process\$5) with thermoelement	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 17:34
27	(computer with (thermoelectric\$5 adj2 cool\$6)) and (((method process\$5) with (thermoelectric\$5 adj2 cool\$5)) ((method process\$5) with thermoelement))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 17:40
12	((("5130276") or ("5228923") or ("5279128") or ("5456081") or ("5867990") or ("5966941") or ("6000225") or ("6060657") or ("6084172") or ("6100463") or ("6161388") or ("6300150")).PN.	USPAT	2003/03/07 17:44
457	fin with (metallic metal) with insulat\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 17:45
1	(peltier with thermoelement) and (fin with (metallic metal) with insulat\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 17:45
229	((62/\$).ccls.) and (thermoelectric adj2 cooler)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 17:45
37	((62/\$).ccls.) and (thermoele\$5 with (coat\$5 overcoat\$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 17:46
6	((62/\$).ccls.) and (thermoelectric adj2 cooler)) and (((62/\$).ccls.) and (thermoele\$5 with (coat\$5 overcoat\$5)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/07 17:46
11798	(fin\$5 point\$5 tip\$5) with (heat\$5 adj3 (pump sink))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/10 15:59

470	((fin\$5 point\$5 tip\$5) with (heat\$5 adj3 (pump sink))) same computer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/10 16:03
38	((fin\$5 point\$5 tip\$5) with (heat\$5 adj3 (pump sink))) same computer) and (thermoelectric peltier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/10 16:01
28	((fin\$5 point\$5 tip\$5) with (heat\$5 adj3 (pump sink))) same (metal metallic) same insulat\$5 same (coat\$5 overcoat\$5 over-coat\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/10 16:10
416	thomas with parsons	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/10 16:11
27855	thermoelectric peltier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/10 16:11
125	(thomas with parsons) and (thermoelectric peltier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/10 16:21